

N-Channel Enhancement Mode Power MOSFET

Description

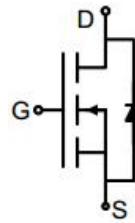
The GT100N12T uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

General Features

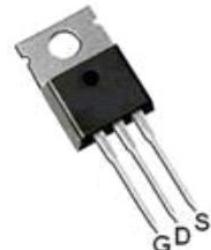
- V_{DS} 120V
- I_D (at $V_{GS} = 10V$) 70A
- $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 10mΩ
- 100% Avalanche Tested
- RoHS Compliant

Application

- Power switch
- DC/DC converters



Schematic diagram



TO-220

Ordering Information

| Device | Package | Marking | Packaging |
|-----------|---------|----------|------------|
| GT100N12T | TO-220 | GT100N12 | 50pcs/Tube |

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Value | Unit |
|--|----------------|------------|------|
| Drain-Source Voltage | V_{DS} | 120 | V |
| Continuous Drain Current | I_D | 70 | A |
| Pulsed Drain Current (note1) | I_{DM} | 280 | A |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Power Dissipation | P_D | 100 | W |
| Single pulse avalanche energy (note2) | E_{AS} | 156 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 To 150 | °C |

Thermal Resistance

| Parameter | Symbol | Value | Unit |
|---|------------|-------|------|
| Thermal Resistance, Junction-to-Ambient | R_{thJA} | 50 | °C/W |
| Maximum Junction-to-Case | R_{thJC} | 1.25 | °C/W |

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Test Conditions | Value | | | Unit |
|--|-----------------------------|--|-------|------|-----------|------------------|
| | | | Min. | Typ. | Max. | |
| Static Parameters | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$ | 120 | -- | -- | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = 120\text{V}, V_{\text{GS}} = 0\text{V}$ | -- | -- | 1 | μA |
| Gate-Source Leakage | I_{GSS} | $V_{\text{GS}} = \pm 20\text{V}$ | -- | -- | ± 100 | nA |
| Gate-Source Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$ | 2 | 3 | 4 | V |
| Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$ | -- | 8 | 10 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{GS}} = 5\text{V}, I_D = 20\text{A}$ | -- | 25 | -- | S |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 60\text{V}, f = 1.0\text{MHz}$ | -- | 2825 | -- | pF |
| Output Capacitance | C_{oss} | | -- | 410 | -- | |
| Reverse Transfer Capacitance | C_{rss} | | -- | 9 | -- | |
| Total Gate Charge | Q_g | $V_{\text{DD}} = 60\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$ | -- | 50 | -- | nC |
| Gate-Source Charge | Q_{gs} | | -- | 17 | -- | |
| Gate-Drain Charge | Q_{gd} | | -- | 15 | -- | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = 60\text{V}, I_D = 20\text{A}, R_G = 1.6\Omega$ | -- | 15 | -- | ns |
| Turn-on Rise Time | t_r | | -- | 10 | -- | |
| Turn-off Delay Time | $t_{\text{d}(\text{off})}$ | | -- | 34 | -- | |
| Turn-off Fall Time | t_f | | -- | 8 | -- | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Body Diode Current | I_S | $T_C = 25^\circ\text{C}$ | -- | -- | 70 | A |
| Body Diode Voltage | V_{SD} | $T_J = 25^\circ\text{C}, I_{\text{SD}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$ | -- | -- | 1.2 | V |
| Reverse Recovery Charge | Q_{rr} | $I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$ | -- | 106 | -- | nC |
| Reverse Recovery Time | T_{rr} | | -- | 60 | -- | ns |

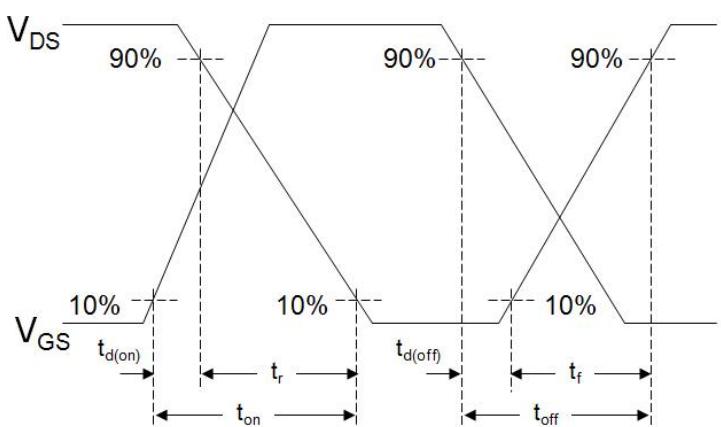
Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
- Identical low side and high side switch with identical R_G

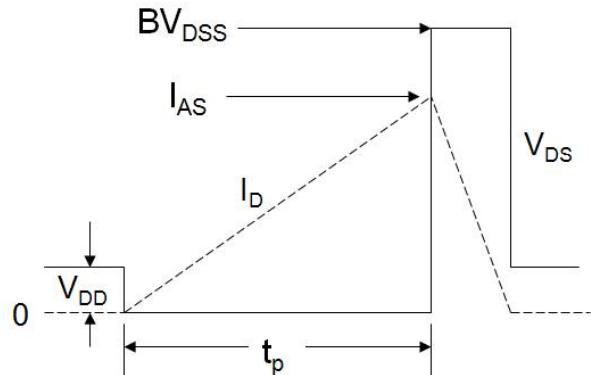
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

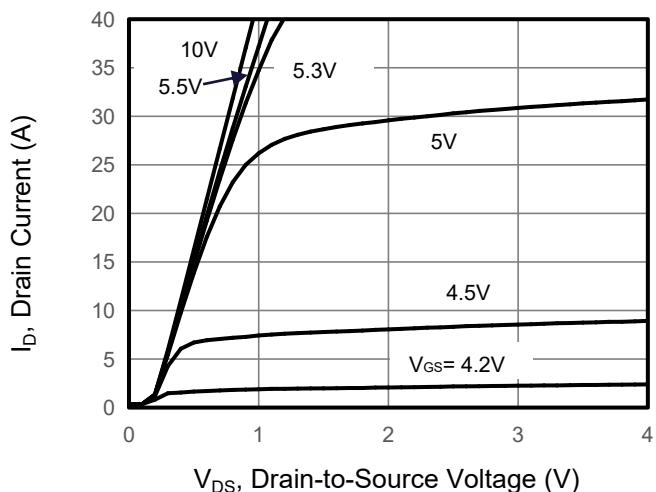


Figure 2. Transfer Characteristics

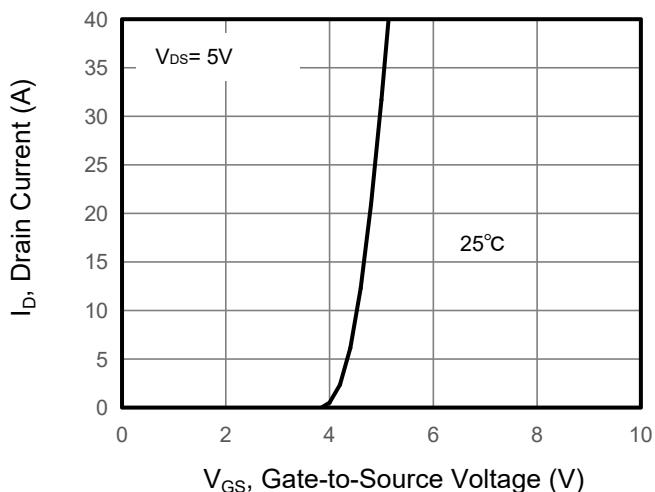


Figure 3. Drain Source On Resistance

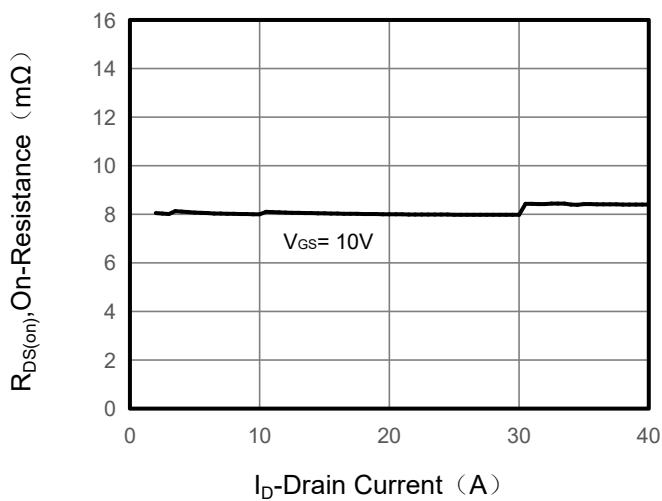


Figure 4. Gate Charge

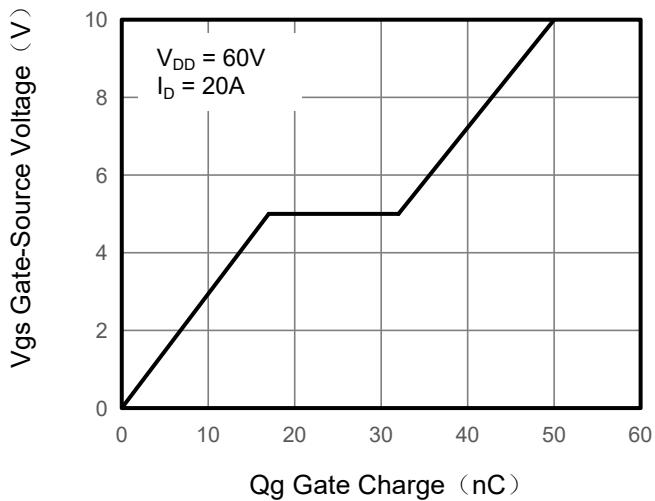


Figure 5. Capacitance

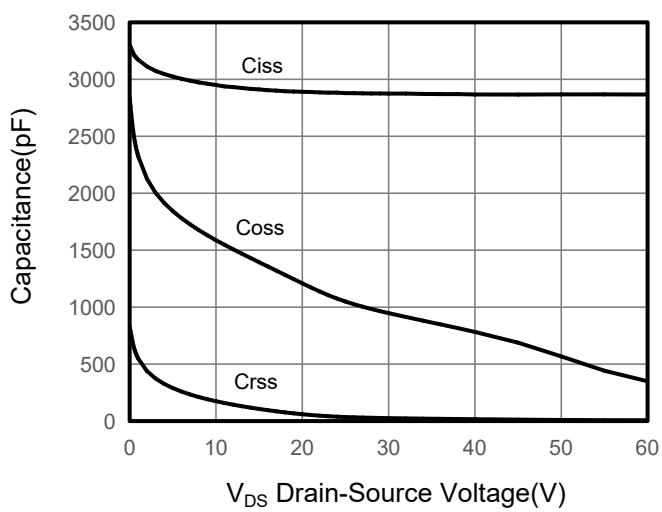
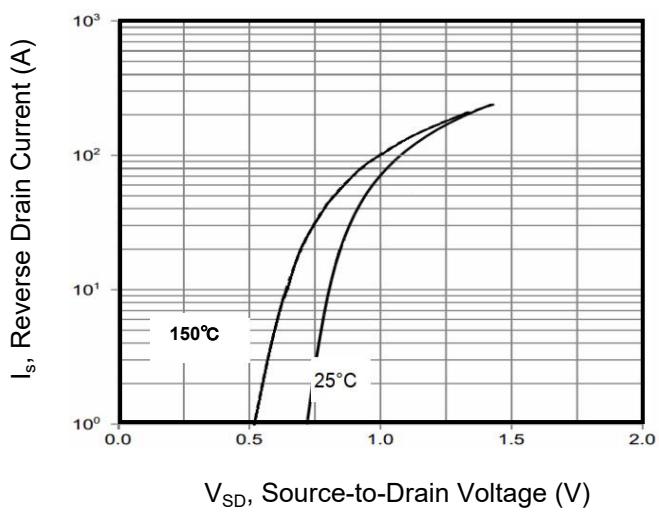


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

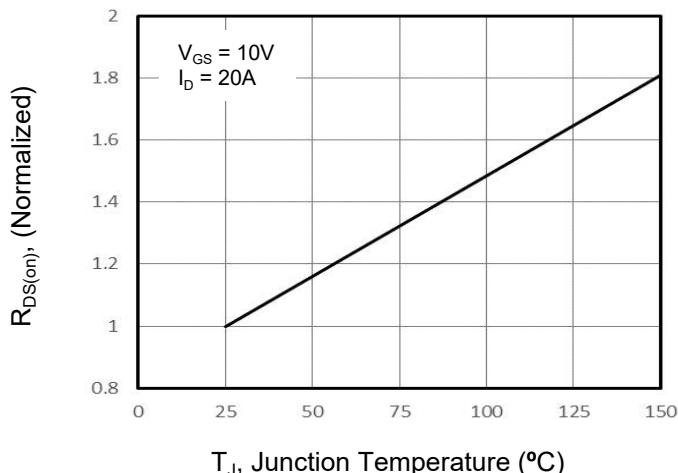


Figure 8. Safe Operation Area

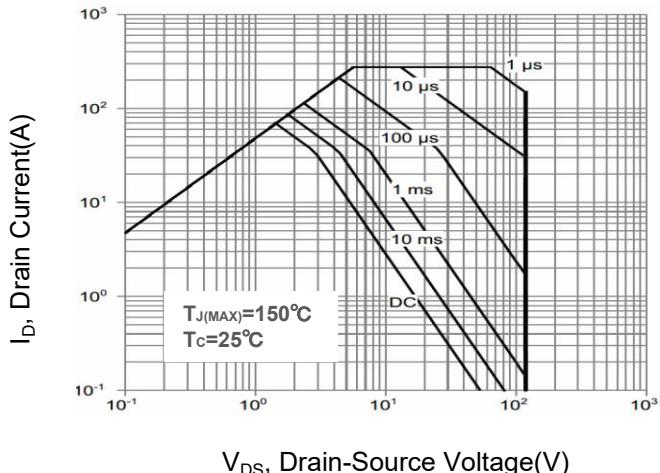
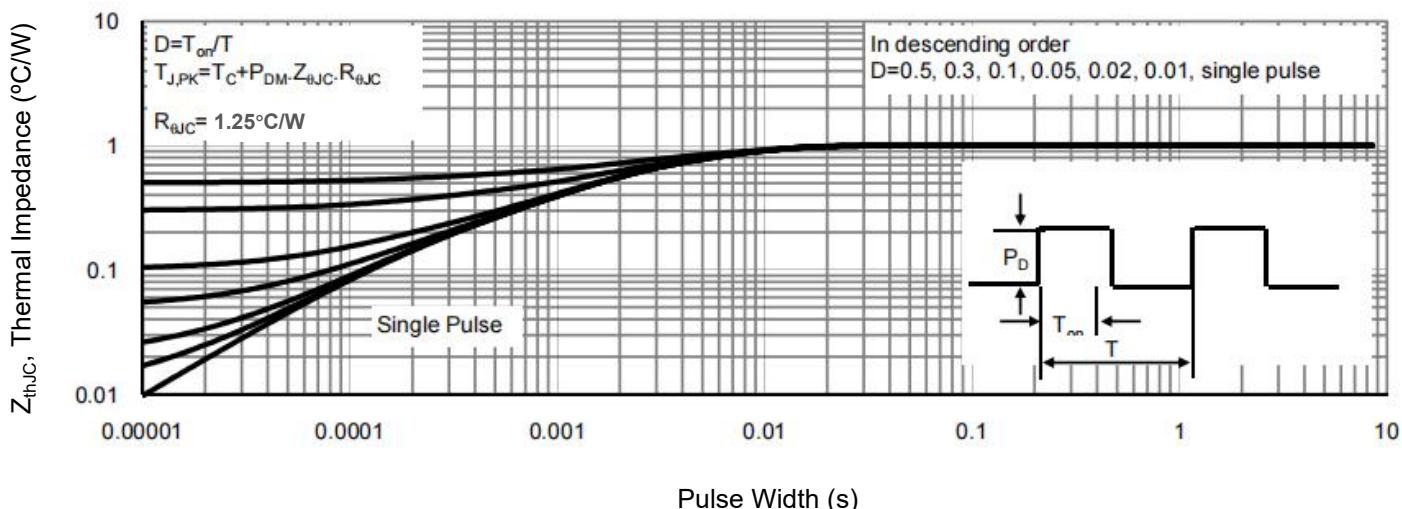
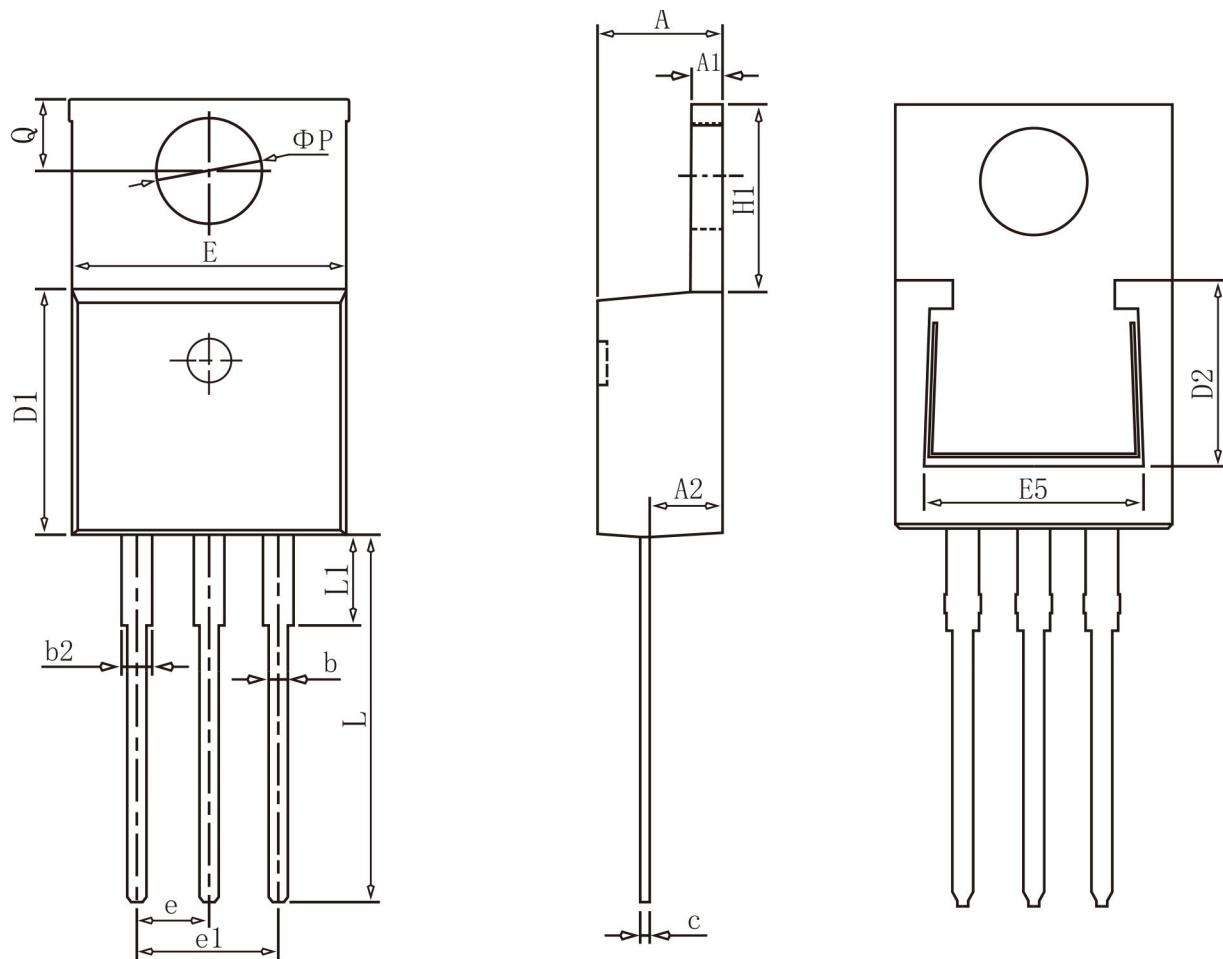


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-220 Package Information



COMMON DIMENSIONS

| SYMBOL | mm | | |
|--------|---------|-------|-------|
| | MIN | NOM | MAX |
| A | 4.37 | 4.57 | 4.77 |
| A1 | 1.22 | 1.27 | 1.42 |
| A2 | 2.49 | 2.69 | 2.89 |
| b | 0.75 | 0.81 | 0.96 |
| b2 | 1.22 | 1.27 | 1.47 |
| c | 0.30 | 0.38 | 0.48 |
| D1 | 8.50 | 8.70 | 8.90 |
| D2 | 5.20 | — | — |
| E | 9.86 | 10.16 | 10.36 |
| E5 | 7.06 | — | — |
| e | 2.54BSC | | |
| e1 | 5.08BSC | | |
| H1 | 6.10 | 6.30 | 6.50 |
| L | 13.10 | 13.40 | 13.70 |
| L1 | — | 3.75 | 4.10 |
| Φ P | 3.70 | 3.84 | 3.99 |
| Q | 2.54 | 2.74 | 2.94 |